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IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Application of: Fukutomi et al.

JUL 2 5 2003 etfal No.:

10/042,408

Group Art Unit: 2813

January 8, 2002

Examiner:

Berezny, Nema O.

Attorney Docket No.: 7426-082

For: Fabrication Process of Semiconductor Package and Semiconductor Package

RESPONSE TO REQUIREMENT FOR RESTRICTION UNDER 37 C.F.R. § 1.142 AND PRELIMINARY AMENDMENT UNDER 37 C.F.R. § 1.115

Mail Stop Non-Fee Amendment Commissioner for Patents P.O. Box 1450 Alexandria, VA 22313-1450

Sir:

In response to the Office Action mailed on June 26, 2003 in connection with the above-identified patent application and in accordance with the Rules of Practice, please enter the following amendments and consider the following remarks. Submitted herewith is Appendix A, revised drawing sheets 1, 3 - 7, 9 - 13, 16 - 21, and 23 - 24.

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